USB 3.0 Promoter Group Announces Feature Complete Ancillary USB Specifications

USB Power Delivery and SuperSpeed USB Inter-Chip Specifications Extend USB Capabilities

BEAVERTON, Ore. – April 11, 2012 – The USB 3.0 Promoter Group today announced that the USB Power Delivery specification and SuperSpeed USB Inter-Chip (SSIC) specification are both on track for completion by the end of Q2 2012. Both specifications are currently at a 0.9 draft completion level, essentially the equivalent of final specifications that implementers can use to start developing products. Prototyping activities to help validate the major technical elements of each specification are well underway and will be completed prior to the final release of these specifications.

The USB power delivery specification will enable increased power delivery via USB cables and connectors, expanding cable bus power capabilities in USB applications. The specification enables higher voltage and current to deliver power up to 100 Watts. It also enables a switchable source of power delivery without changing cable direction. The specification is compatible with existing cables and connectors and will coexist with the USB Battery Charging 1.2 specification and existing USB bus-powered applications.

The SSIC specification will define a chip-to-chip USB based interconnect optimized for mobile device internal use. The specification will bring the MIPI Alliance’s M-PHY™ high bandwidth and low power capabilities combined with the performance enhancements of SuperSpeed USB.

“The USB 3.0 Promoter Group continues to develop practical specifications to support more platform types and new use cases, which benefit from SuperSpeed USB,” said Brad Saunders, USB 3.0 Promoter Group Chairman. “The industry reviews for the USB Power Delivery and SSIC specifications have proven successful, and it is exciting to see these specifications come to fruition.”

The USB Power Delivery and SuperSpeed USB Inter-Chip specifications will be discussed during a USB session at the Intel Developer Forum (IDF) being held April 11-12, 2012 in Beijing. The USB 3.0 Promoter Group intends to transition the final specifications to the USB Implementers Forum (USB-IF) for publication and establishment of the ecosystems and associated compliance programs by the end of Q2 2012.

About SuperSpeed USB

SuperSpeed USB brings significant performance enhancements to the ubiquitous USB standard, while remaining compatible with the billions of USB-enabled devices currently deployed in the market. SuperSpeed USB delivers up to 10x the data transfer rate of Hi-Speed.
USB, as well as improved power efficiency. SuperSpeed USB offers effortless video streaming, music and photos at your home, office, car and anywhere in between. The USB 3.0 specification was developed by the USB 3.0 Promoter Group, which consists of Hewlett-Packard Company, Intel Corporation, Microsoft Corporation, Renesas Electronics, ST-Ericsson and Texas Instruments.

About the USB-IF

The non-profit USB Implementers Forum, Inc. was formed to provide a support organization and forum for the advancement and adoption of USB technology. USB-IF facilitates the development of high-quality, compatible USB devices through its logo and compliance program recognized around the globe and promotes the benefits of USB and the quality of products that have passed compliance testing. Further information, including postings of the most recent product and technology announcements, is available by visiting the USB-IF website at www.usb.org

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